1. Clean mating surfaces of heatsink and FPGA chip with alcohol.
2. Bond heatsink item 2 to FPGA chip on local control board using adhesive. Item 3.
3. Carefully push downward on heatsink to squeeze out excess adhesive before curing.
4. Allow to dry (recommended cure time 48 hours at 20% minimum relative humidity).
5. Trim excess cured adhesive around edges.